

Filename: ProD1BB.IMP
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TIDA-01496 REV E2 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1	1	10uF	CGA5L3X5R1H106M160AB	TDK	CAP, CERM, 10 uF, 50 V, +/- 20%, X5R, AEC-Q200 Grade 3, 1206	1206
2	C2	1	0.1uF	GRM31C5C1E104JA01L	MuRata	CAP, CERM, 0.1 uF, 25 V, +/- 5%, C0G/NP0, 1206	1206
3	C3	1	0.01uF	C0603C103K5RACTU	Kemet	CAP, CERM, 0.01 uF, 50 V, +/- 10%, X7R, 0603	0603
4	C4	1	10uF	C1608X6S1A106M080AC	TDK	CAP, CERM, 10 uF, 10 V, +/- 10%, X6S, 0603	0603
5	C5, C6	2	1uF	GRM188R60J105KA01D	MuRata	CAP, CERM, 1 uF, 6.3 V, +/- 10%, X5R, 0603	0603
6	C7	1	0.1uF	C1206C104K5RACTU	Kemet	CAP, CERM, 0.1 uF, 50 V, +/- 10%, X7R, 1206	1206
7	C8	1	2200pF	08055A222JAT2A	AVX	CAP, CERM, 2200 pF, 50 V, +/- 5%, C0G/NP0, 0805	0805
8	C9	1	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1 uF, 50 V, +/- 10%, X7R, 0603	0603
9	C10	1	10uF	C1608X5R1E106M080AC	TDK	CAP, CERM, 10 uF, 25 V, +/- 20%, X5R, 0603	0603
10	C11	1	470pF	06035A471JAT2A	AVX	CAP, CERM, 470 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
11	D1	1	30V	MBR230LSFT1G	ON Semiconductor	Diode, Schottky, 30 V, 2 A, AEC-Q101, SOD-123FL	SOD-123FL
12	J1, J3	2		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	3x1 Header
13	J2	1		TSW-104-07-G-S	Samtec	Header, 100mil, 4x1, Gold, TH	4x1 Header
14	L1	1	47uH	784777470	Würth Elektronik	Inductor, Shielded, Ferrite, 47 uH, 1.15 A, .3 ohm, AEC-Q200 Grade 1, SMD	7.3x7.3mm
15	R1, R2, R3, R4, R5	5	4.75k	CRCW06034K75FKEA	Vishay-Dale	RES, 4.75 k, 1%, 0.1 W, AEC-Q200 Grade 0, 0603	0603
16	R6	1	47k	CRCW060347K0JNEA	Vishay-Dale	RES, 47 k, 5%, 0.1 W, AEC-Q200 Grade 0, 0603	0603
17	R10, R11, R12	3	0	CRCW20100000Z0EF	Vishay-Dale	RES, 0, 5%, 0.75 W, AEC-Q200 Grade 0, 2010	2010
18	U1	1		DRV10983SQPWPRQ1	Texas Instruments	Automotive, Three-Phase, Sensorless BLDC Motor Driver, PWP0024B (TSSOP-24)	PWP0024B
19	U2	1		MSP430G25531PW0RQ1	Texas Instruments	MSP430(TM) Ultra-Low-Power Microcontrollers for Automotive Applications, PW0020A (TSSOP-20)	PW0020A
20	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A

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